

FIG. 1

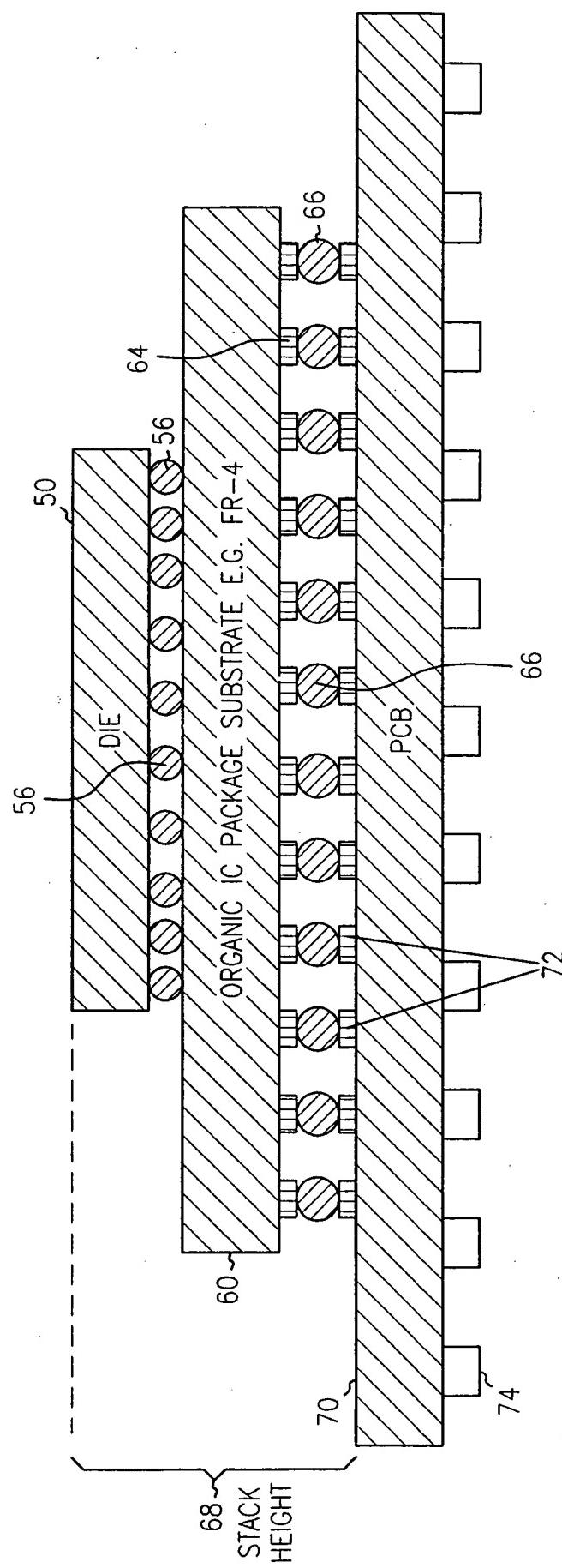


FIG. 2
(PRIOR ART)

3/12

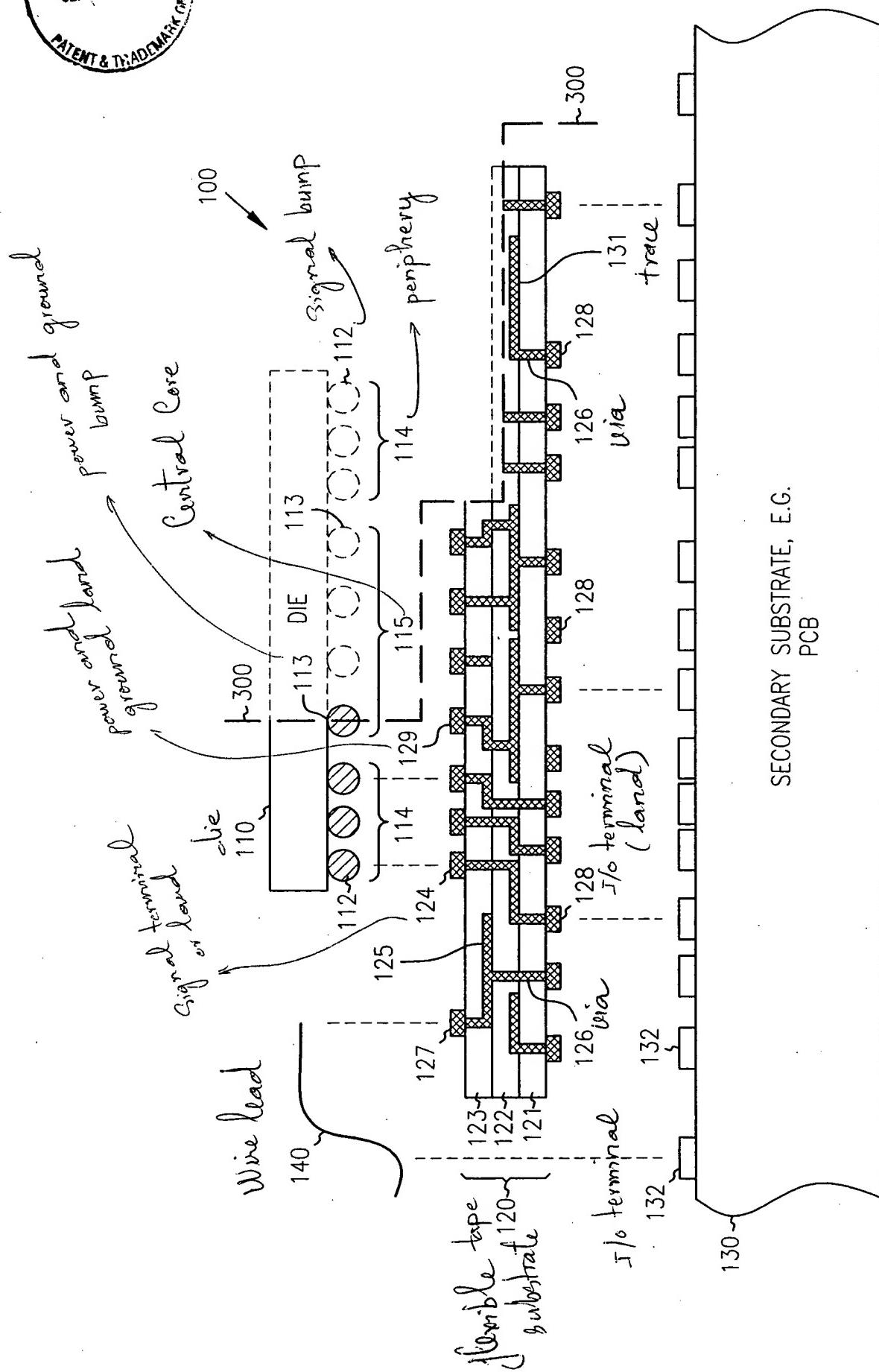


FIG. 3

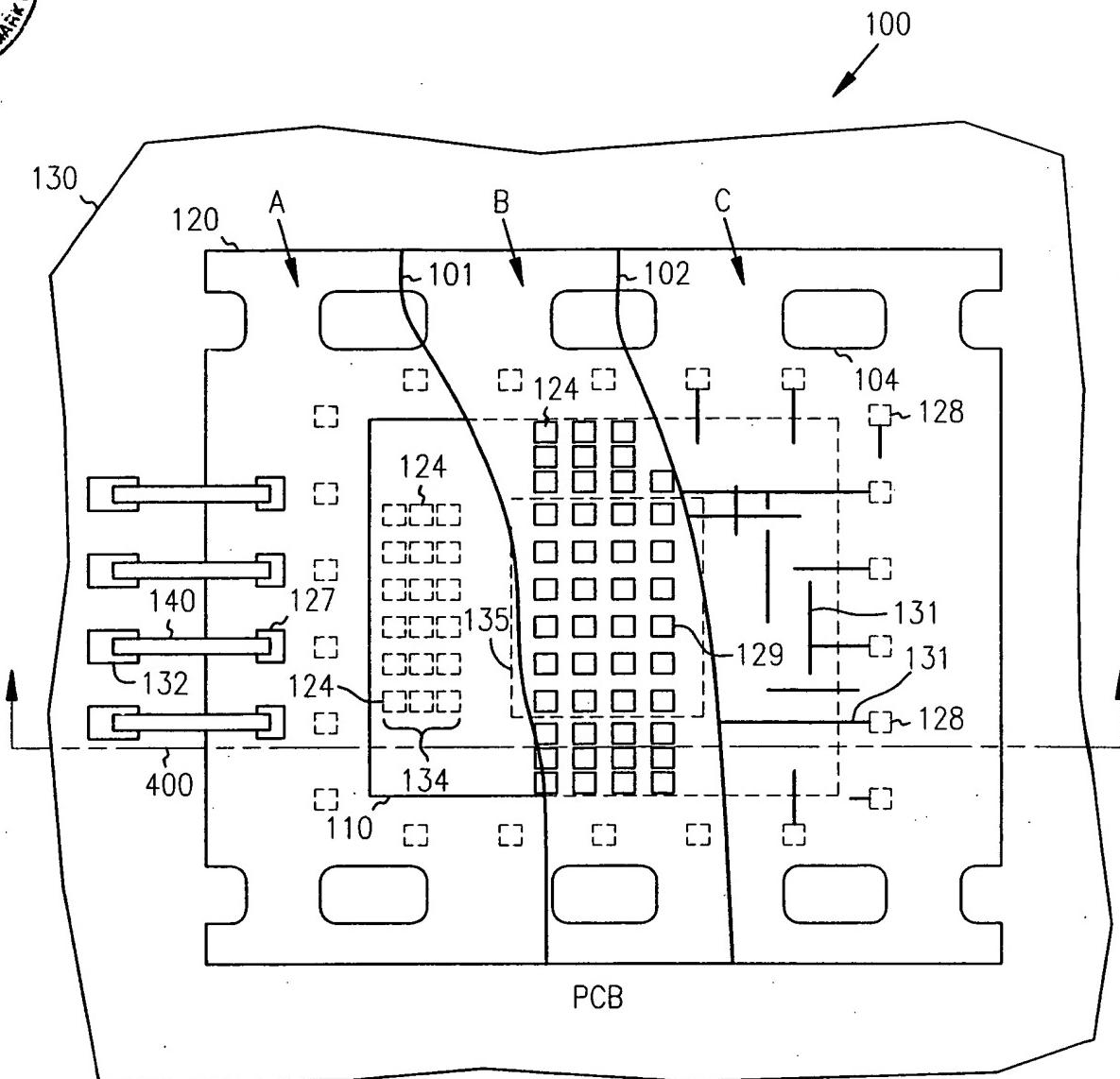


FIG. 4

5/12

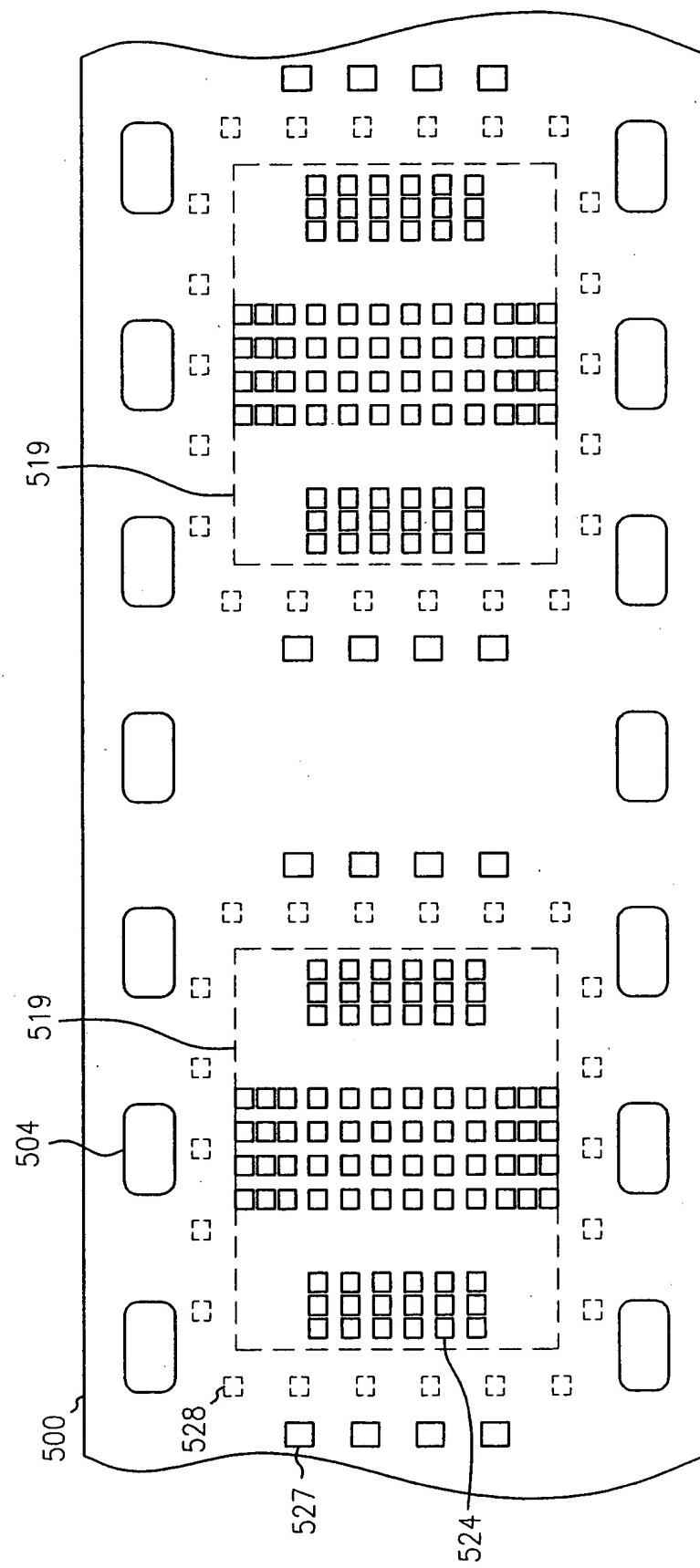


FIG. 5

INVENTORS NAME: Ajit V. Sathre
SERIAL NO.: 09/893,036

6/12

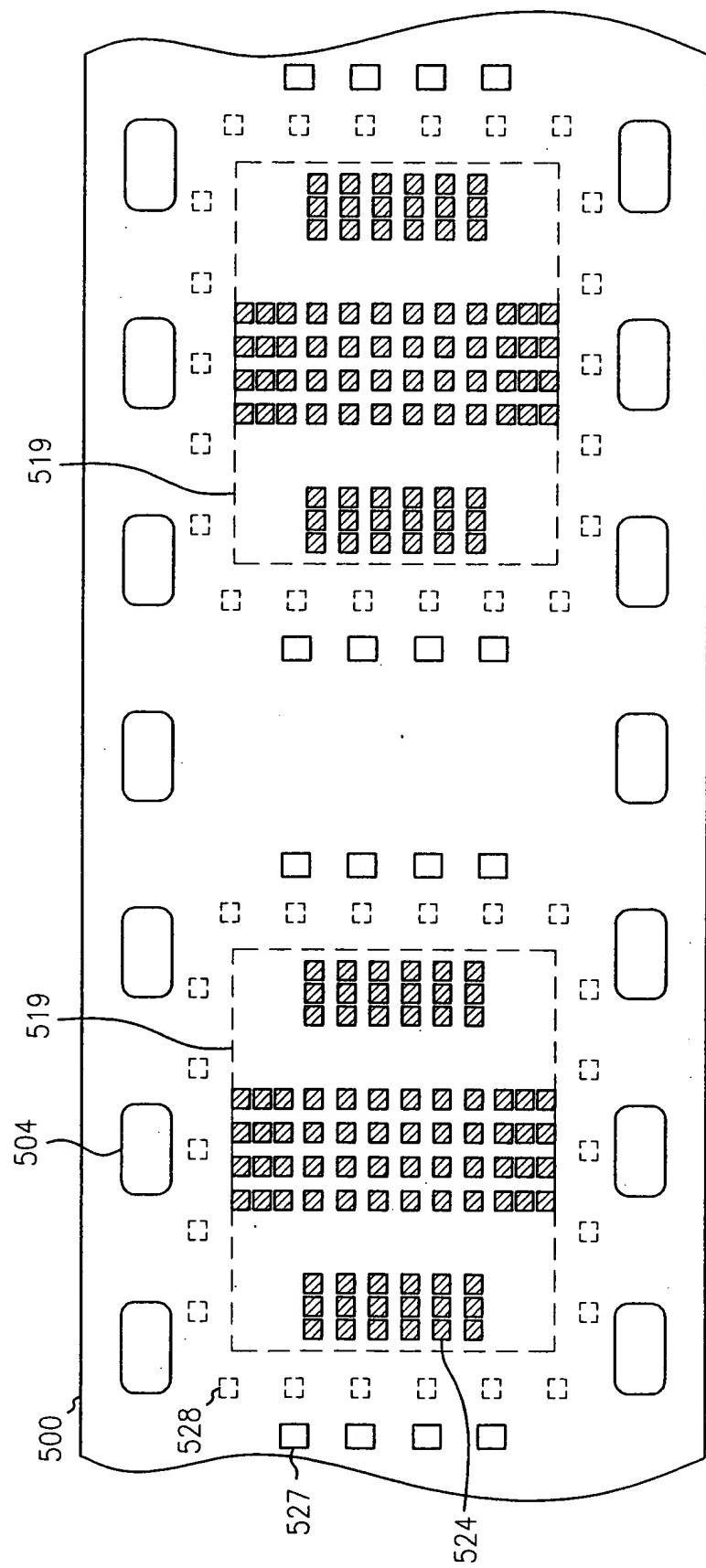


FIG. 6

7/12

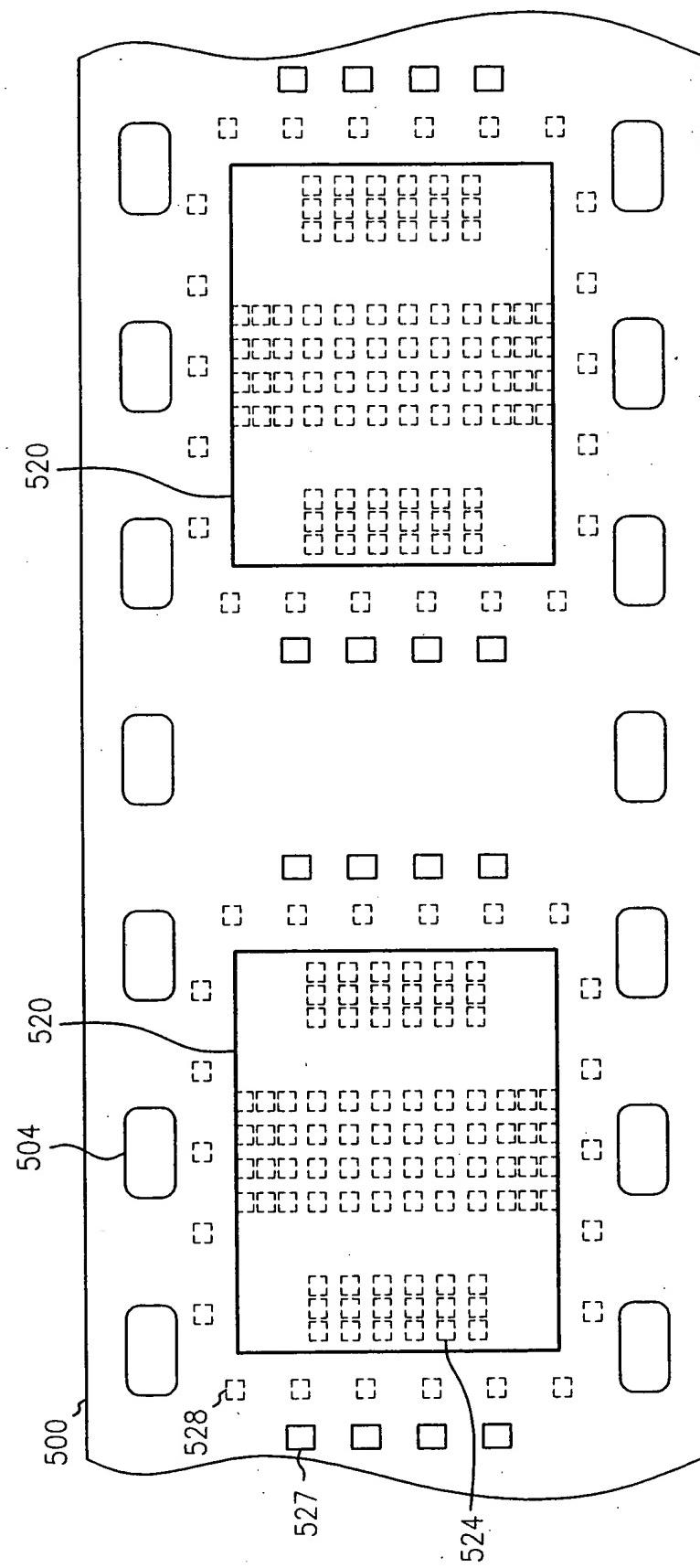


FIG. 7

8/12

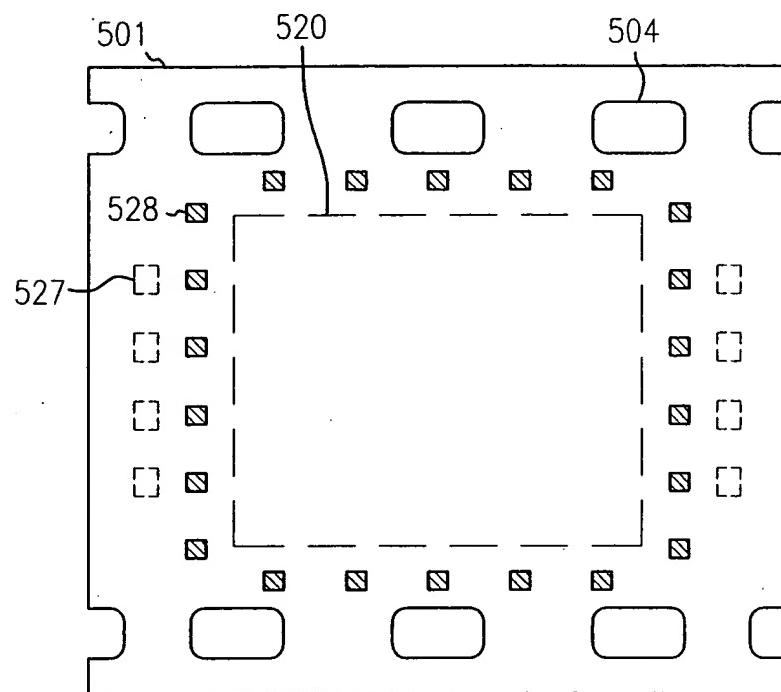


FIG. 8

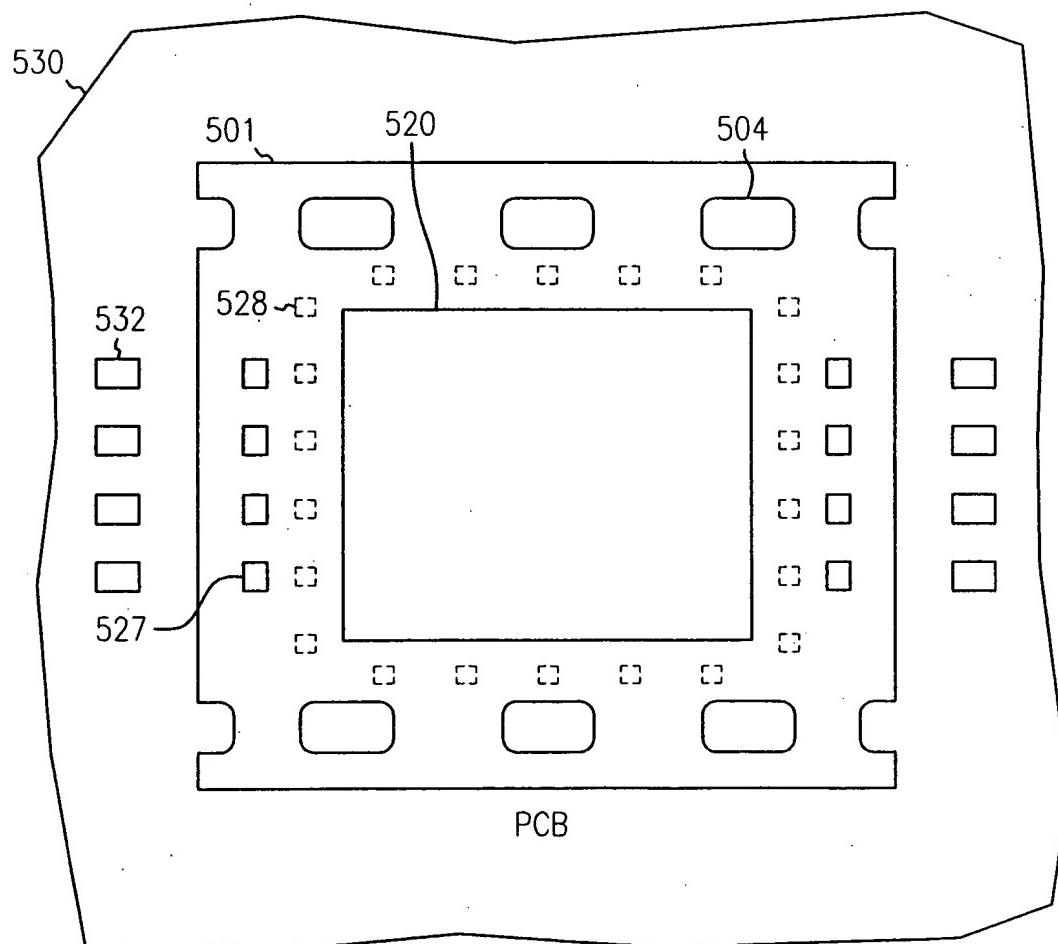


FIG. 9

9/12

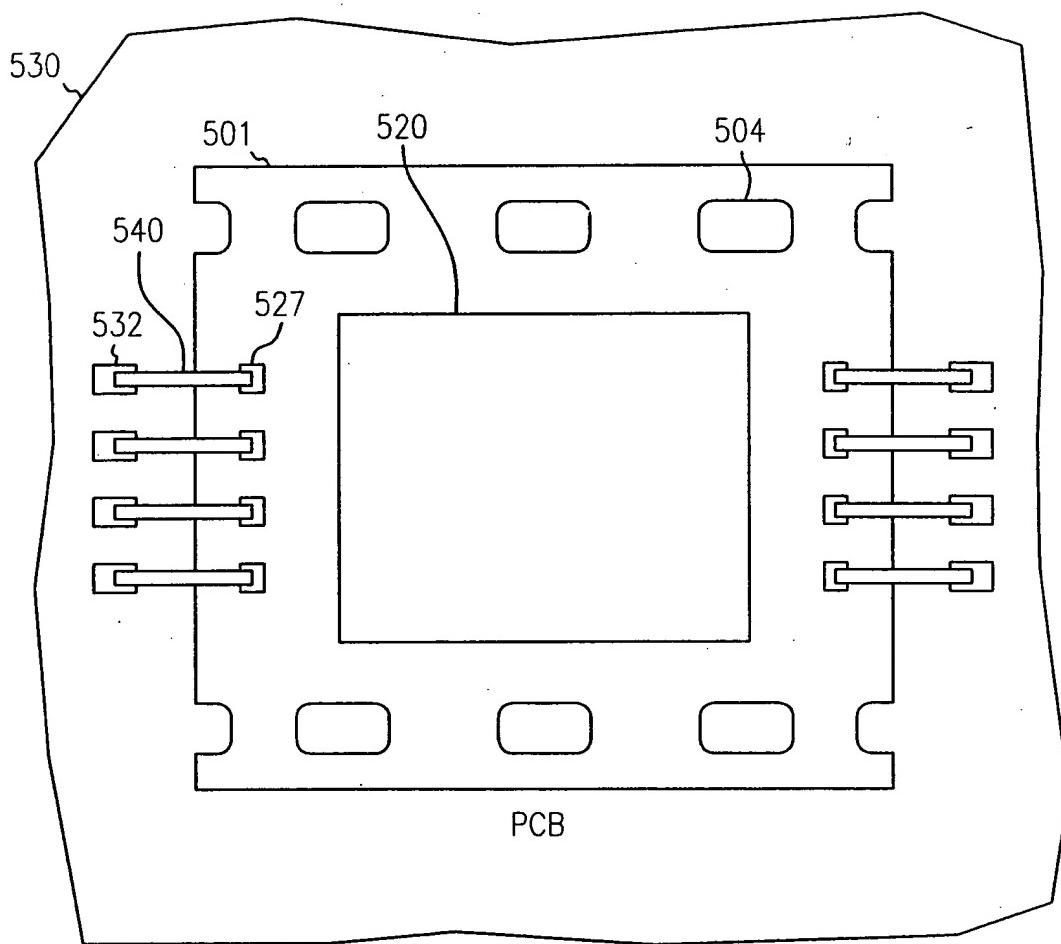


FIG. 10



10/12.

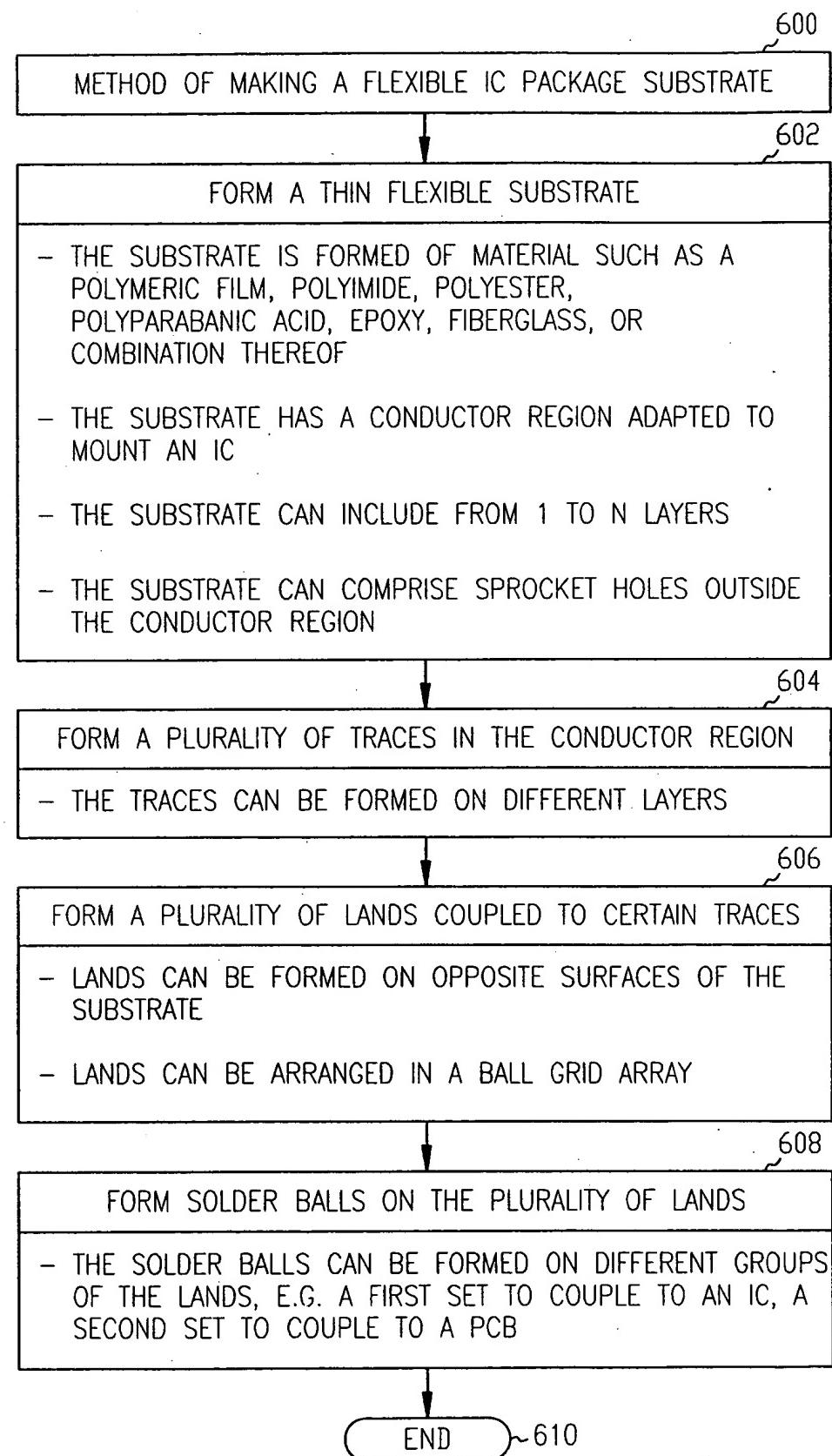


FIG. 11

11/12

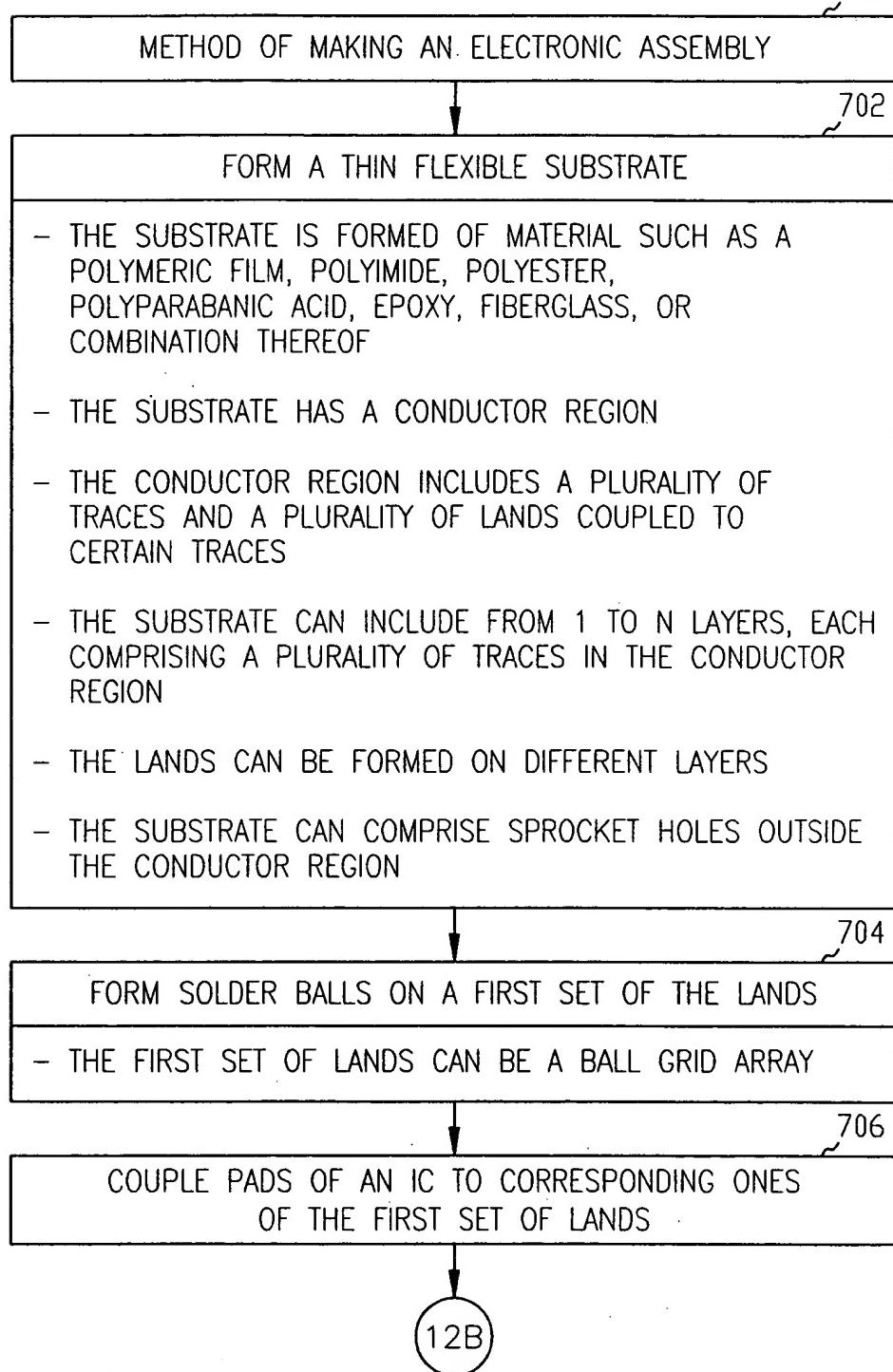


FIG. 12A

12/12



12A

708

MOUNT THE SUBSTRATE ON AN ADDITIONAL
SUBSTRATE, E.G. A PCB

EMPLOY EITHER OR BOTH OF THE FOLLOWING:

- USE BGA BETWEEN SUBSTRATE AND PCB
 - FORM SOLDER BALLS ON A SECOND SET OF THE LANDS
 - COUPLE ONES OF THE SECOND SET OF LANDS TO CORRESPONDING TERMINALS ON THE PCB

- USE LEADS BETWEEN SUBSTRATE AND PCB
 - COUPLE LEADS, E.G. WIRES, BETWEEN CORRESPONDING ONES OF A THIRD SET OF LANDS AND ADDITIONAL TERMINALS OF THE PCB

END

~710

FIG. 12B